



Appendix 3 Product End-of-Life Disassembly instructions

Product Identification:

Marketing Name / Model	Description
HP ProLiant DL585	4U 4 Processor Server

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product.
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 square cm	16
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 square cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB / PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		26
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials		0



containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T-15
Philips Screw Driver	#2
Flat Head Screw Driver	Medium

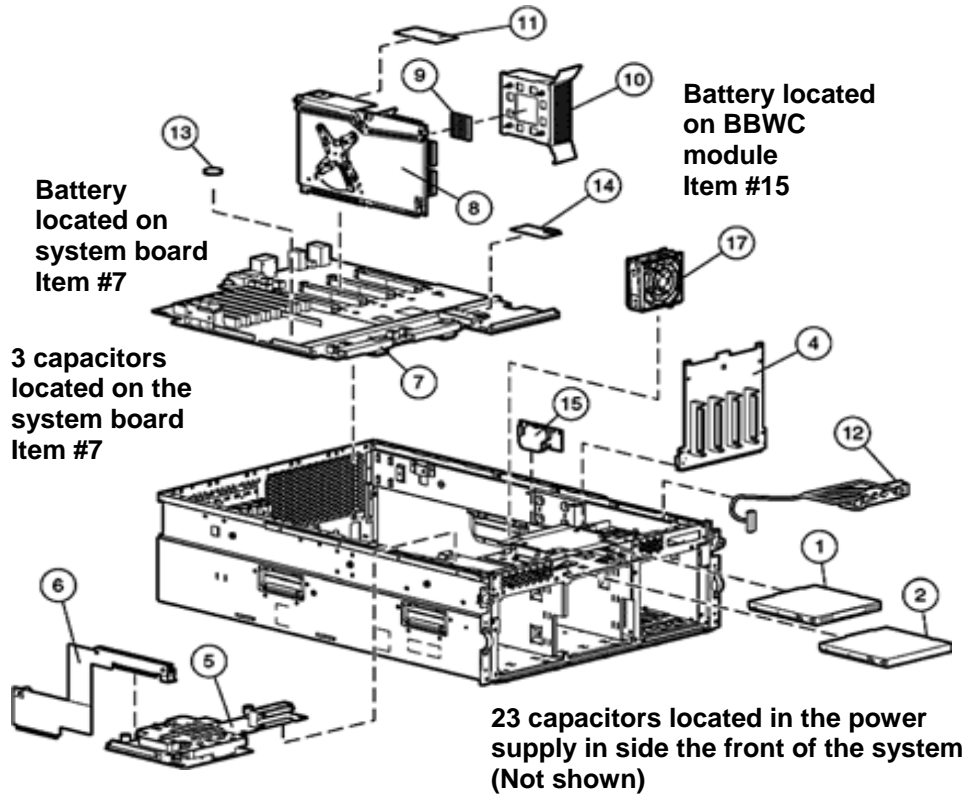
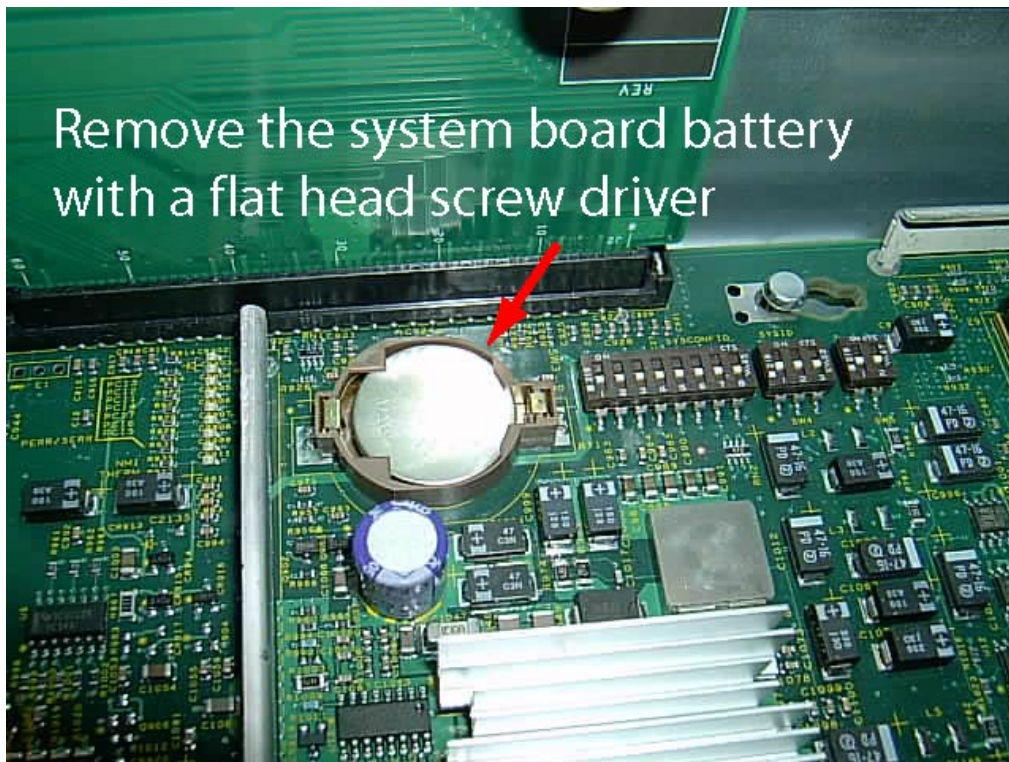
3.0 Product Disassembly Process

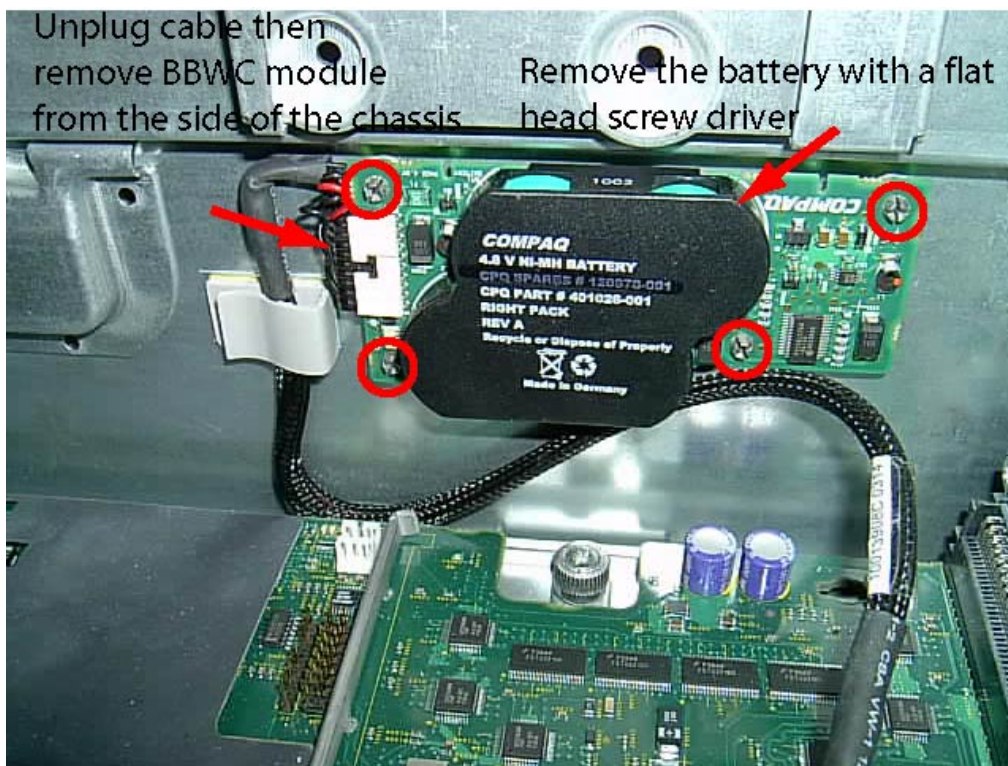
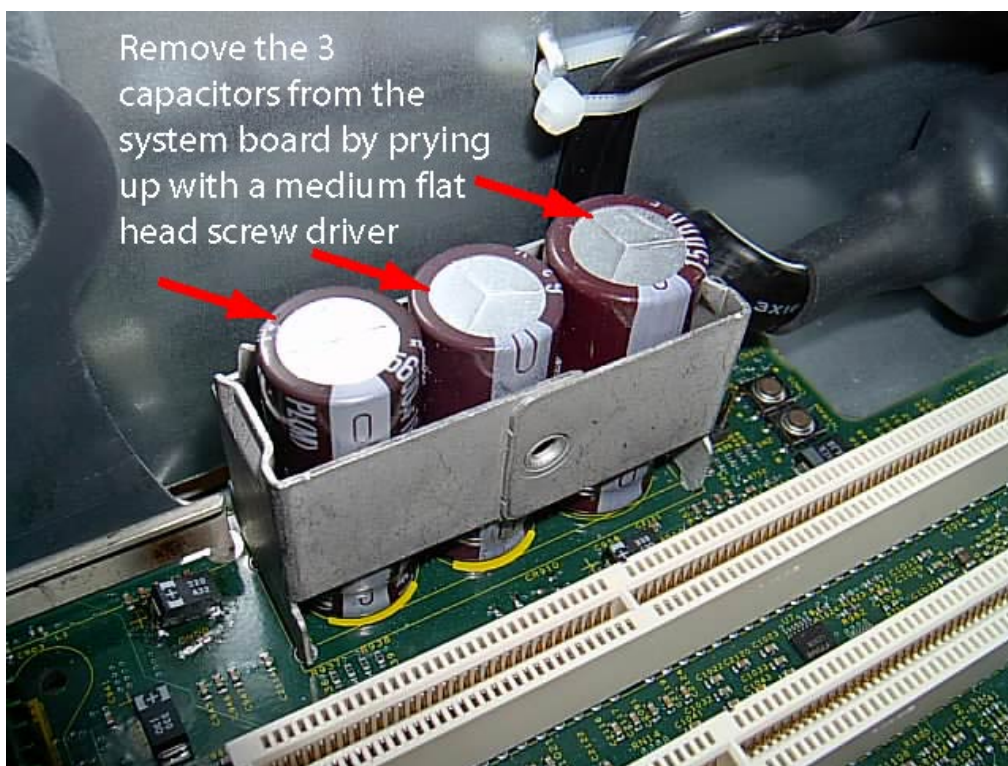
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

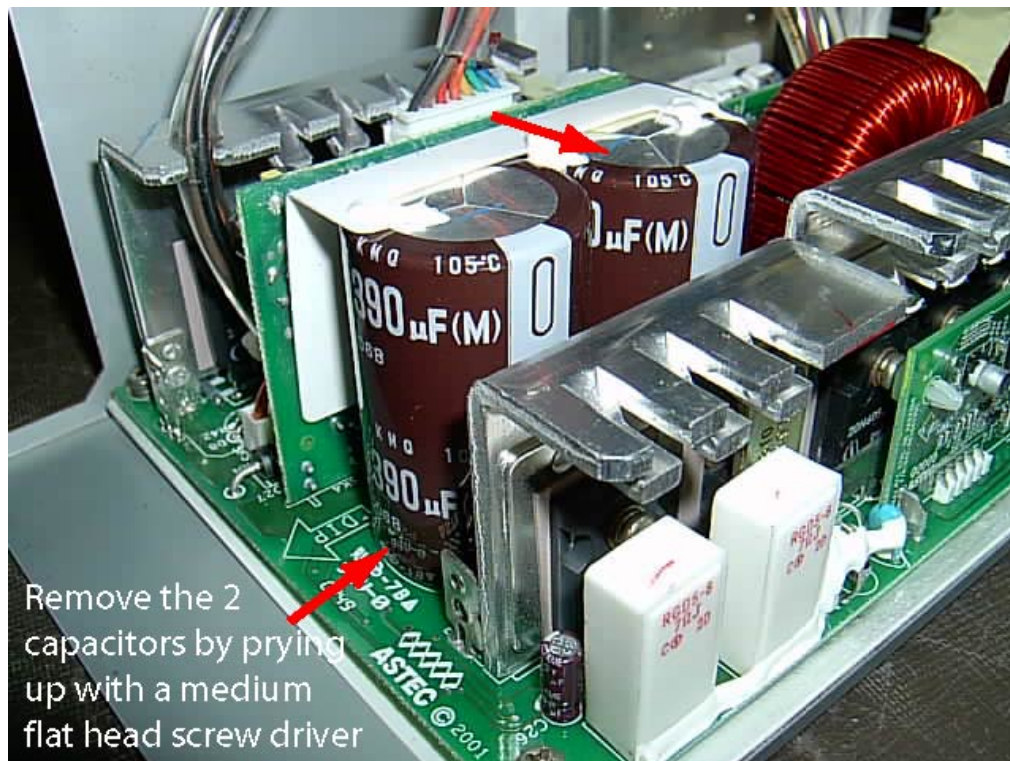
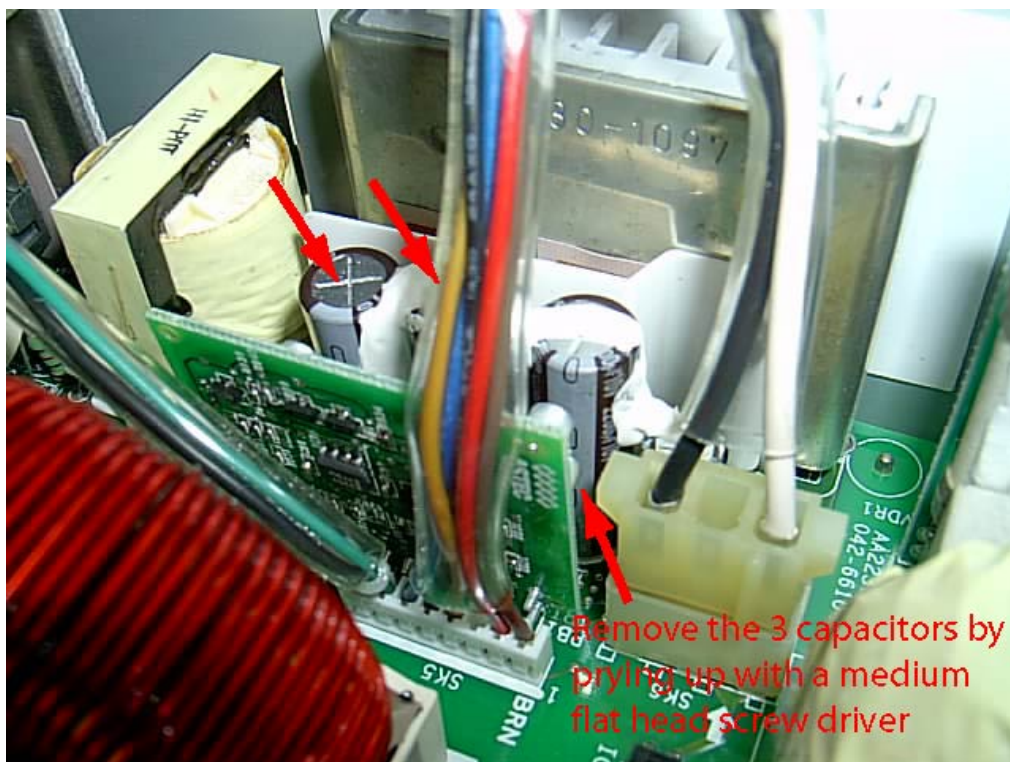
1	System Board Battery – Remove the top cover and locate the battery on the system board. With a medium flat head screw driver remove the battery and dispose of properly.
2	Battery Backed Module – With the top cover removed locate the BBWC module with the battery on the side of the chassis then remove and dispose of properly.
3	Capacitors > 2.5CM – With the top cover removed locate the capacitors on the system board and pry from the PCB with a medium flat head screw driver and dispose of properly.
4	Capacitors > 2.5CM – Remove the power supply(s) from the system. With #2 Philips screw driver remove the screws securing the top cover then locate the capacitors and pry from the PCB with a medium flat head screw driver and dispose of properly.
5	
6	
7	

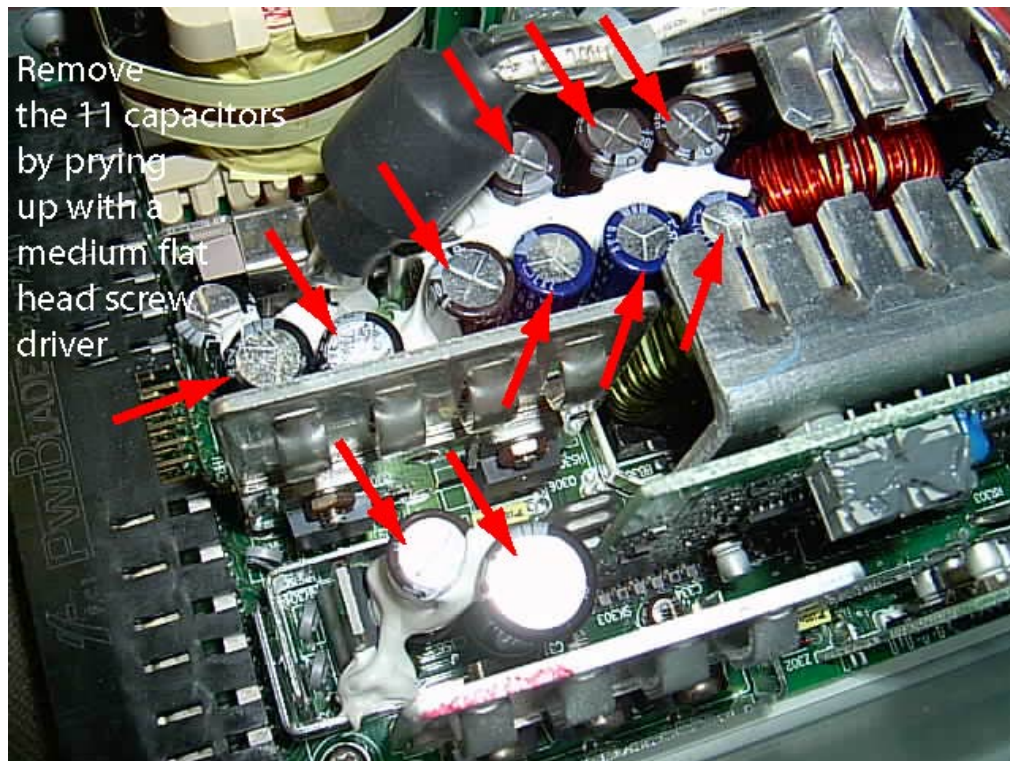
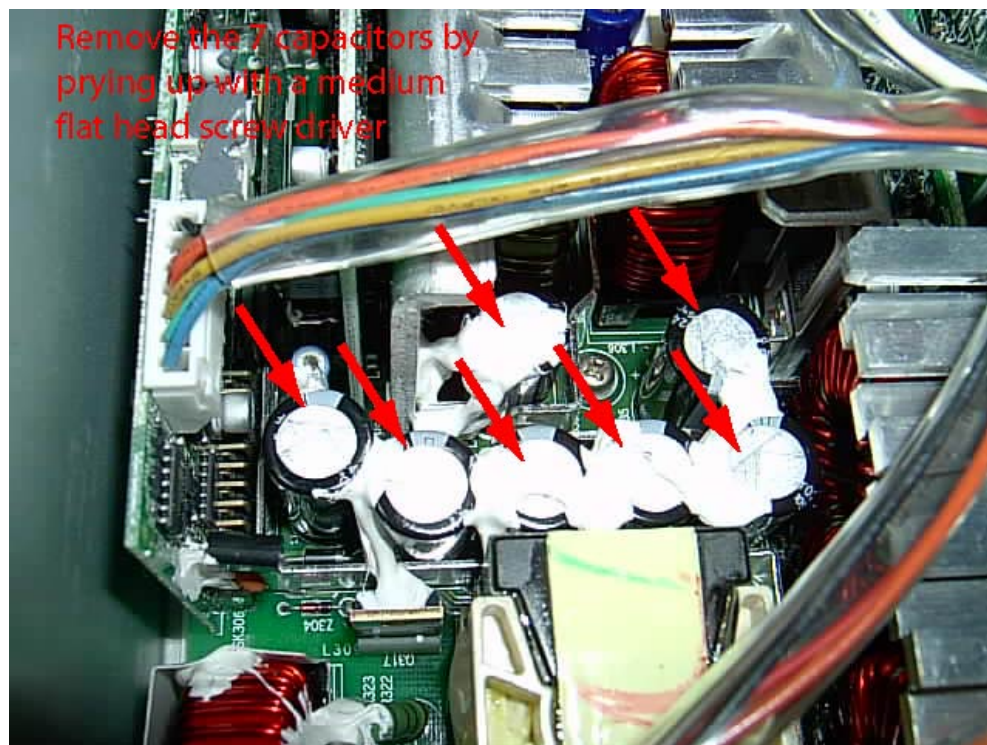
3.2 OPTIONAL: Depending upon the complexity of the disassembly process, a graphic depicting the locations of items contained within the product which require selective treatment (with descriptions and arrows identifying locations) can be inserted below:

Attachment 1 – Disassembly Diagram
Attachment 2 – System Battery Location
Attachment 3 – Battery Backed Module Location
Attachment 4 – System Board Capacitor Location
Attachment 5, 6, 7 & 8 – Power Supply Capacitor Locations

Attachment 1Attachment 2

**Attachment 3****Attachment 4**

**Attachment 5****Attachment 6**

Attachment 7Attachment 8